

IPC/JEDEC J-STD-035



Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components

A joint standard developed by the EIA/JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

Users of this standard are encouraged to participate in the development of future revisions.

Contact:

EIA/JEDEC

Engineering Department 2500 Wilson Boulevard Arlington, VA 22201 Phone (703) 907-7500 Fax (703) 907-7501

IPC

2215 Sanders Road Northbrook, IL 60062-6135 Phone (847) 509-9700 Fax (847) 509-9798 April 1999 IPC/JEDEC J-STD-035

Table of Contents

1 S	COPE
2 D	EFINITIONS
2.1	A-mode
2.2	B-mode
2.3	Back-Side Substrate View Area 1
2.4	C-mode
2.5	Through Transmission Mode
2.6	Die Attach View Area 2
2.7	Die Surface View Area
2.8	Focal Length (FL)
2.9	Focus Plane
2.10	$Leadframe \ (L/F) \ View \ Area \ \ldots \qquad 2$
2.11	Reflective Acoustic Microscope 2
2.12	Through Transmission Acoustic Microscope 2
2.13	Time-of-Flight (TOF)
2.14	Top-Side Die Attach Substrate View Area 3
3 A	PPARATUS
3.1	Reflective Acoustic Microscope System 3
3.2	Through Transmission Acoustic Microscope System
4 P	ROCEDURE 4
4.1	Equipment Setup
4.2	Perform Acoustic Scans

Appendix A	Sheet 6		
Appendix B	Potential Image Pitfalls 9		
Appendix C	Some Limitations of Acoustic Microscopy 10		
Appendix D	Reference Procedure for Presenting Applicable Scanned Data		
Figures			
Figure 1	Example of A-mode Display1		
Figure 2	Example of B-mode Display1		
Figure 3	Example of C-mode Display 2		
Figure 4	Example of Through Transmission Display 2		
0	Diagram of a Reflective Acoustic Microscope System3		
	Diagram of a Through Transmission Acoustic Microscope System 3		

April 1999 IPC/JEDEC J-STD-035

Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components

1 SCOPE

This test method defines the procedures for performing acoustic microscopy on non-hermetic encapsulated electronic components. This method provides users with an acoustic microscopy process flow for detecting defects non-destructively in plastic packages while achieving reproducibility.

2 DEFINITIONS

2.1 A-mode Acoustic data collected at the smallest X-Y-Z region defined by the limitations of the given acoustic microscope. An A-mode display contains amplitude and phase/polarity information as a function of time of flight at a single point in the X-Y plane. See Figure 1 - Example of A-mode Display.

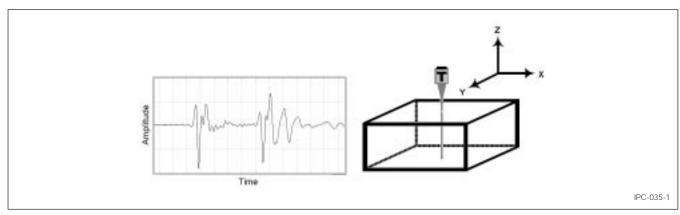


Figure 1 Example of A-mode Display

2.2 B-mode Acoustic data collected along an X-Z or Y-Z plane versus depth using a reflective acoustic microscope. A B-mode scan contains amplitude and phase/polarity information as a function of time of flight at each point along the scan line. A B-mode scan furnishes a two-dimensional (cross-sectional) description along a scan line (X or Y). See Figure 2 - Example of B-mode Display.

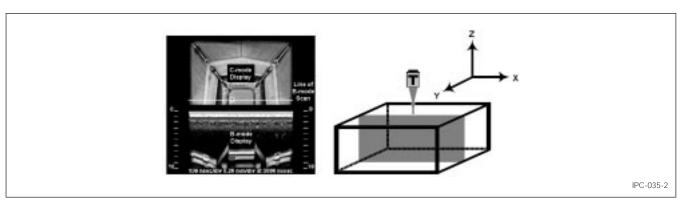


Figure 2 Example of B-mode Display (bottom half of picture on left)

- **2.3 Back-Side Substrate View Area (Refer to Appendix A, Type IV)** The interface between the encapsulant and the back of the substrate within the outer edges of the substrate surface.
- **2.4 C-mode** Acoustic data collected in an X-Y plane at depth (Z) using a reflective acoustic microscope. A C-mode scan contains amplitude and phase/polarity information at each point in the scan plane. A C-mode scan furnishes a two-dimensional (area) image of echoes arising from reflections at a particular depth (Z). See Figure 3 Example of C-mode Display.